

Thin Film Magnetic Head

[Name of Document] Abstract of the Disclosure

[Abstract]

[Object]

A thin film magnetic head having a reduced thermal protrusion with respect to an ambient temperature rise is provided.

[Solving Means]

A magnetic material having a low coefficient of thermal expansion of $11.5 \times 10^{-6}/K$ or less is used for forming at least one of a lower shield or an upper shield. A laminated film consisting of a layer of the magnetic material having a low coefficient of thermal expansion of $11.5 \times 10^{-6}/K$ or less and an 80 wt% NiFe alloy layer is used for forming at least one of the lower shield and the upper shield. Thus, the thin film magnetic head having reduced noise after recording and reduced thermal protrusion can be obtained.

[Selected Drawing] Fig. 1